

Data Sheet

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*±*15kV ESD Protected, 20Mbps, 5V, Low Power, RS-485/RS-422 Transceiver

The Intersil ISL4485E is a high speed, BiCMOS 5V powered, single transceiver that meets both the RS-485 and RS-422 standards for balanced communication. Each driver output/receiver input is protected against ± 15 kV ESD strikes, without latch-up. Unlike competitive devices, this Intersil device is specified for 10% tolerance supplies (4.5V to 5.5V).

The excellent differential output voltage coupled with high drive-current output stages allow 20Mbps operation over twisted pair networks up to 450 feet in length. The $25k\Omega$ receiver input resistance presents a "single unit load" to the RS-485 bus, allowing up to 32 transceivers on the network.

Receiver (Rx) inputs feature a "fail-safe if open" design, which ensures a logic high Rx output if Rx inputs are floating.

Driver (Tx) outputs are short circuit protected, even for voltages exceeding the power supply voltage. Additionally, on-chip thermal shutdown circuitry disables the Tx outputs to prevent damage if power dissipation becomes excessive.

The half duplex configuration multiplexes the Rx inputs and Tx outputs to allow transceivers with Rx and Tx disable functions in 8 lead packages.

Ordering Information

PART NO. (BRAND)	TEMP. RANGE (^o C)	PACKAGE	PKG. DWG. #
ISL4485EIB (44 <mark>85EIB)</mark>	-40 to 85	8 Ld SOIC	M8.15
ISL <mark>4485EIBZ</mark> (4485EIBZ) (See Note)	-40 to 85	8 Ld SOIC (Pb-free)	M8.15
ISL4485EIB-T (4485EIB)	-40 to 85	8 Ld SOIC Tape & Reel	M8.15
ISL4485EIBZ-T (4485EIBZ) (See Note)	-40 to 85	8 Ld SOIC Tape & Reel (Pb-free)	M8.15

NOTE: Intersil Pb-free products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

Features

- Pb-Free Available (RoHS Compliant)
- High Data Rates..... up to 20Mbps
- RS-485 I/O Pin ESD Protection ±15kV HBM
- Class 3 ESD Level on all Other Pins >7kV HBM
- Operates from a Single +5V Supply (10% Tolerance)
- 1 Unit Load Allows up to 32 Devices on the Bus
- -7V to +12V Common Mode Input Voltage Range
- Three State Rx and Tx Outputs
- 30ns Propagation Delays, 2ns Skew
- Current Limiting and Thermal Shutdown for driver Overload Protection

Applications

- SCSI "Fast 20" Drivers and Receivers
- Data Loggers
- Security Networks
- Building Environmental Control Systems
- Industrial/Process Control Networks
- Level Translators

Pinout





Truth Tables

TRANSMITTING							
INPUTS OUTPUTS							
RE	DE	DI	B/Z A/Y				
Х	1	1	0	1			
Х	1	0	1	0			
Х	0	Х	High-Z	High-Z			

RECEIVING							
	INPUTS	OUTPUT					
RE	DE	A-B	RO				
0	0	≥ +0.2V	1				
0	0	\leq -0.2V	0				
0	0	Inputs Open	1				
1	Х	Х	High-Z				

Pin Descriptions

PIN	FUNCTION
RO	Receiver output: If A > B by at least 0.2V, RO is high; If A < B by 0.2V or more, RO is low; RO = High if A and B are unconnected (floating).
RE	Receiver output enable. RO is enabled when \overline{RE} is low; RO is high impedance when \overline{RE} is high.
DE	Driver output enable. The driver outputs, Y and Z, are enabled by bringing DE high. They are high impedance when DE is low.
DI	Driver input. A low on DI forces output Y low and output Z high. Similarly, a high on DI forces output Y high and output Z low.
GND	Ground connection.
A/Y	\pm 15kV HBM ESD Protected, noninverting receiver input and noninverting driver output. Pin is an input (A) if DE = 0; pin is an output (Y) if DE = 1.
B/Z	\pm 15kV HBM ESD Protected, inverting receiver input and inverting driver output. Pin is an input (B) if DE = 0; pin is an output (Z) if DE = 1.
V _{CC}	System power supply input (4.5V to 5.5V).

Typical Operating Circuit



Absolute Maximum Ratings

V _{CC} to Ground
Input Voltages
DI, DE, RE
Input / Output Voltages
A / Y, B / Z
RO
Short Circuit Duration
Y, Z Continuous
ESD Rating See Specification Table
-

Operating Conditions

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} (°C/W)
8 Ld SOIC Package	170
Maximum Junction Temperature (Plastic Package)	150 ⁰ C
Maximum Storage Temperature Range	^o C to 150 ^o C
Maximum Lead Temperature (Soldering 10s) (Lead Tips Only)	300 ⁰ C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. θ_{JA} is measured with the component mounted on a low effective thermal conductivity test board in free air. See Tech Brief TB379 for details.

$\label{eq:conditions: V_{CC} = 4.5V to 5.5V; Unless Otherwise Specified.} Typicals are at V_{CC} = 5V, T_A = 25^oC, Note 2$

PARAMETER	SYMBOL	TEST CONDITIONS			MIN	ТҮР	МАХ	UNITS
DC CHARACTERISTICS				I				
Driver Differential V _{OUT} (no load)	V _{OD1}			Full	-	-	V _{CC}	V
Driver Differential V _{OUT} (with load)	V _{OD2}	R = 50Ω (RS-422), (Figu	ure 1)	Full	2	3	-	V
		R = 27Ω (RS-485), (Figu	ure 1)	Full	1.5	2.3	5	V
Change in Magnitude of Driver Differential V _{OUT} for Complementary Output States	ΔV_{OD}	$R = 27\Omega$ or 50Ω , (Figure	R = 27 Ω or 50 Ω , (Figure 1)		-	0.01	0.2	V
Driver Common-Mode VOUT	V _{OC}	R = 27Ω or 50Ω , (Figure	: 1)	Full	-	-	3	V
Change in Magnitude of Driver Common-Mode V _{OUT} for Complementary Output States	ΔV _{OC}	R = 27 Ω or 50 Ω , (Figure 1)		Full	-	0.01	0.2	V
Logic Input High Voltage	VIH	DE, DI, RE		Full	2	-	-	V
Logic Input Low Voltage	VIL	DE, DI, RE		Full	-	-	0.8	V
Logic Input Current	I _{IN1}	DE, DI, RE	DE, DI, RE		-25	-	25	μA
Input Current (A, B), (Note 5)	I _{IN2}	$DE = 0V, V_{CC} = 0V \text{ or } \qquad V_{IN} = 12V$		Full	-	-	1	mA
		4.5 to 5.5V	V _{IN} = -7V	Full	-	-	-0.8	mA
Receiver Differential Threshold Voltage	V _{TH}	$-7V \le V_{CM} \le 12V$		Full	-0.2	-	0.2	V
Receiver Input Hysteresis	ΔV_{TH}	$V_{CM} = 0V$		25	-	70	-	mV
Receiver Output High Voltage	V _{OH}	$I_{O} = -4mA, V_{ID} = 200mV$	1	Full	3.5	4	-	V
Receiver Output Low Voltage	V _{OL}	$I_{O} = -4mA, V_{ID} = 200mV$	1	Full	-	0.1	0.4	V
Three-State (high impedance) Receiver Output Current	I _{OZR}	$0.4V \le V_O \le 2.4V$		Full	-	-	±1	μΑ
Receiver Input Resistance	R _{IN}	$-7V \le V_{CM} \le 12V$		Full	12	25	-	kΩ
No-Load Supply Current, (Note 3)	ICC	DI, $\overline{RE} = 0V$ or V_{CC} DE = V_{CC}		Full	-	700	900	μA
			DE = 0V	Full	-	500	565	μA
Driver Short-Circuit Current, $V_O =$ High or Low	I _{OSD1}	$DE = V_{CC}, \ \text{-7V} \le V_{Y} \text{ or } V_{Z} \le 12V, \text{ (Note 4)}$		Full	35	-	250	mA
Receiver Short-Circuit Current	IOSR	$0V \le V_O \le V_{CC}$		Full	7	-	85	mA

Electrical Specifications

Test Conditions: V_{CC} = 4.5V to 5.5V; Unless Otherwise Specified. Typicals are at V_{CC} = 5V, T_A = 25^oC, Note 2 **(Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	ТҮР	MAX	UNITS	
SWITCHING CHARACTERISTICS								
Driver Input to Output Delay	t _{PLH} , t _{PHL}	$R_{DIFF} = 54\Omega, C_{L} = 100pF, (Figure 2)$	Full	15	30	50	ns	
Driver Output Skew	^t SKEW	$R_{DIFF} = 54\Omega, C_{L} = 100pF, (Figure 2)$	Full	-	1.3	5	ns	
Driver Differential Rise or Fall Time	t _R , t _F	$R_{DIFF} = 54\Omega$, $C_L = 100pF$, (Figure 2)	Full	3	11	25	ns	
Driver Enable to Output High	^t ZH	$C_L = 100 pF$, SW = GND, (Figure 3)	Full	-	17	30	ns	
Driver Enable to Output Low	t _{ZL}	$C_L = 100 pF, SW = V_{CC}, (Figure 3)$	Full	-	14	30	ns	
Driver Disable from Output High	t _{HZ}	$C_L = 15pF$, SW = GND, (Figure 3)	Full	-	19	30	ns	
Driver Disable from Output Low	t _{LZ}	$C_L = 15pF, SW = V_{CC}, (Figure 3)$	Full	-	13	30	ns	
Driver Maximum Data Rate	f _{MAXD}	$ V_{OD} \ge 1.5V$, (Figure 4, Note 6)	Full	20	-	-	Mbps	
Receiver Input to Output Delay	t _{PLH} , t _{PHL}	Figure 5	Full	20	40	70	ns	
Receiver Skew t _{PLH} - t _{PHL}	^t SKD	Figure 5	Full	-	3	10	ns	
Receiver Enable to Output High	t _{ZH}	$C_L = 15pF$, SW = GND, (Figure 6)	Full	-	9	25	ns	
Receiver Enable to Output Low	t _{ZL}	$C_L = 15pF, SW = V_{CC}, (Figure 6)$	Full	-	9	25	ns	
Receiver Disable from Output High	t _{HZ}	$C_L = 15pF$, SW = GND, (Figure 6)	Full	-	9	25	ns	
Receiver Disable from Output Low	t _{LZ}	$C_L = 15pF, SW = V_{CC}, (Figure 6)$	Full	-	9	25	ns	
Receiver Maximum Data Rate	f _{MAXR}	$C_L = 15 pF, V_{ID} \ge 1.5 V \text{ (Note 6)}$	Full	20	-	-	Mbps	
ESD PERFORMANCE								
RS-485 Pins (A/Y, B/Z)		Human Body Model	25	-	±15	-	kV	
All Other Pins			25	-	>±7	-	kV	

NOTE:

2. All currents into device pins are positive; all currents out of device pins are negative. All voltages are referenced to device ground unless otherwise specified.

3. Supply current specification is valid for loaded drivers when DE = 0V.

4. Applies to peak current. See "Typical Performance Curves" for more information.

5. Devices meeting these limits are denoted as "single unit load (1 UL)" transceivers. The RS-485 standard allows up to 32 Unit Loads on the bus.

6. Guaranteed by characterization, but not tested.

Test Circuits and Waveforms



FIGURE 1. DRIVER VOD AND VOC



FIGURE 3A. TEST CIRCUIT

FIGURE 3B. MEASUREMENT POINTS

FIGURE 3. DRIVER ENABLE AND DISABLE TIMES



Application Information

RS-485 and RS-422 are differential (balanced) data transmission standards for use in long haul or noisy environments. RS-422 is a subset of RS-485, so RS-485 transceivers are also RS-422 compliant. RS-422 is a pointto-multipoint (multidrop) standard, which allows only one driver and up to 10 (assuming one unit load devices) receivers on each bus. RS-485 is a true multipoint standard, which allows up to 32 one unit load devices (any combination of drivers and receivers) on each bus. To allow for multipoint operation, the RS-485 spec requires that drivers must handle bus contention without sustaining any damage.

Another important advantage of RS-485 is the extended common mode range (CMR), which specifies that the driver outputs and receiver inputs withstand signals that range from +12V to -7V. RS-422 and RS-485 are intended for runs as long as 4000', so the wide CMR is necessary to handle ground potential differences, as well as voltages induced in the cable by external fields.

Receiver Features

The ISL4485E utilizes a differential input receiver for maximum noise immunity and common mode rejection. Input sensitivity is ± 200 mV, as required by the RS-422 and RS-485 specifications.

Receiver input impedance surpasses the RS-422 spec of $4k\Omega$, and meets the RS-485 "Unit Load" requirement of $12k\Omega$ minimum.

Receiver inputs function with common mode voltages as great as \pm 7V outside the power supplies (i.e., +12V and -7V), making them ideal for long networks where induced voltages are a realistic concern.

The receiver includes a "fail-safe if open" function that guarantees a high level receiver output if the receiver inputs are unconnected (floating). The output is three-statable via the active low $\overline{\mathsf{RE}}$ input, and the receiver easily meets the 20Mbps data rate.

Driver Features

The RS-485/422 driver is a differential output device that delivers at least 1.5V across a 54 Ω load (RS-485), and at least 2V across a 100 Ω load (RS-422). The ISL4485E driver features low propagation delay skew to maximize bit width, and to minimize EMI, and the outputs are three-statable via the active high DE input.

Outputs of ISL4485E drivers are not slew rate limited, so faster output transition times allow data rates up to 20Mbps.

Data Rate, Cables, and Terminations

Twisted pair is the cable of choice for RS-485/422 networks. Twisted pair cables tend to pick up noise and other electromagnetically induced voltages as common mode signals, which are effectively rejected by the differential receivers in these ICs.

RS-485/422 are intended for network lengths up to 4000', but the maximum transmission length decreases as the data rate increases. According to guidelines in the RS-422 specification, a 20Mbps network should be limited to less than 50' of 24 AWG twisted pair. Nevertheless, the ISL4485E's large differential voltage swing, fast transition times, and high drive-current output stages allow operation at 20Mbps in RS-485/422 networks as long as 450'. Figure 7 details ISL4485E operation at 20Mbps driving 300' of CAT 5 cable terminated in 120Ω at the driver and the receiver (i.e., double terminated). The acceptance criteria for this test was the ability of the driver to deliver a 1.5V differential signal to the receiver at the end of the cable (i.e., $|A-B| \ge 1.5V$). If a more liberal acceptance criteria is used, the distance can be further extended. For example, Figure 8 illustrates the performance in the same configuration, but with a cable length of 450', and an acceptance criteria of no more than 6dB attenuation across the cable (i.e., |A-B| = |Y-Z|/2).

Driver differential output voltage decreases with increasing differential load capacitance, so maintaining a 1.5V differential output requires a data rate reduction, as shown in Figure 9.

To minimize reflections, proper termination is imperative when using this 20Mbps device. In point-to-point, or point-tomultipoint (single driver on bus) networks, the main cable should be terminated in its characteristic impedance (typically 120 Ω) at the end farthest from the driver. In multireceiver applications, stubs connecting receivers to the main cable should be kept as short as possible (preferably less than 12 inches). Multipoint (multi-driver) systems require that the main cable be terminated in its characteristic impedance at both ends. Again, stubs connecting a transceiver to the main cable should be kept as short as possible.

Built-In Driver Overload Protection

As stated previously, the RS-485 spec requires that drivers survive worst case bus contentions undamaged. The ISL4485E device meets this requirement via driver output short circuit current limits, and on-chip thermal shutdown circuitry.

The driver output stages incorporate short circuit current limiting circuitry which ensures that the output current never exceeds the RS-485 spec, even at the common mode voltage range extremes. Additionally, these devices utilize a foldback circuit which reduces the short circuit current, and thus the power dissipation, whenever the contending voltage exceeds either supply.

In the event of a major short circuit condition, this device also includes a thermal shutdown feature that disables the drivers whenever the die temperature becomes excessive. This eliminates the power dissipation, allowing the die to cool. The drivers automatically reenable after the die temperature drops about 15 degrees. If the contention persists, the thermal shutdown / reenable cycle repeats until the fault is cleared. Receivers stay operational during thermal shutdown.

ESD Protection

All pins on these interface devices include class 3 Human Body Model (HBM) ESD protection structures, but the RS-485 pins (driver outputs and receiver inputs) incorporate advanced structures allowing them to survive ESD events in excess of ± 15 kV HBM. The RS-485 pins are particularly vulnerable to ESD damage because they typically connect to an exposed port on the exterior of the finished product. Simply touching the port pins, or connecting a cable, can cause an ESD event that might destroy unprotected ICs. These new ESD structures protect the device whether or not it is powered up, protect without allowing any latchup mechanism to activate, and without degrading the RS-485 common mode range of -7V to +12V. This built-in ESD protection eliminates the need for board level protection structures (e.g., transient suppression diodes), and the associated, undesirable capacitive load they present.

Human Body Model Testing

As the name implies, this test method emulates the ESD event delivered to an IC during human handling. The tester delivers the charge stored on a 100pF capacitor through a $1.5k\Omega$ current limiting resistor into the pin under test. The HBM method determines an ICs ability to withstand the ESD events typically present during handling and manufacturing.

The RS-485 pin survivability on this high ESD device has been characterized to be in excess of $\pm 15 kV,$ for discharges to GND.



Typical Performance Curves $V_{CC} = 5V$, $T_A = 25^{\circ}C$; Unless Otherwise Specified

FIGURE 7. DRIVER AND RECEIVER WAVEFORMS DRIVING 300 FEET OF CABLE (DOUBLE TERMINATED)





FIGURE 8. DRIVER AND RECEIVER WAVEFORMS DRIVING 450 FEET OF CABLE (DOUBLE TERMINATED)



FIGURE 10. SUPPLY CURRENT vs TEMPERATURE



Typical Performance Curves $V_{CC} = 5V$, $T_A = 25^{\circ}C$; Unless Otherwise Specified (Continued)



Typical Performance Curves V_{CC} = 5V, T_A = 25^oC; Unless Otherwise Specified (Continued)

Die Characteristics

SUBSTRATE POTENTIAL (POWERED UP):

GND

TRANSISTOR COUNT:

518

PROCESS:

Si Gate CMOS

Small Outline Plastic Packages (SOIC)



NOTES:

- 1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
- 2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
- Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
- 5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
- 6. "L" is the length of terminal for soldering to a substrate.
- 7. "N" is the number of terminal positions.
- 8. Terminal numbers are shown for reference only.
- 9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
- 10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

M8.15 (JEDEC MS-012-AA ISSUE C) 8 LEAD NARROW BODY SMALL OUTLINE PLASTIC PACKAGE

	INCHES		MILLIMETERS		
SYMBOL	MIN	MAX	MIN MAX		NOTES
A	0.0532	0.0688	1.35	1.75	-
A1	0.0040	0.0098	0.10	0.25	-
В	0.013	0.020	0.33	0.51	9
С	0.0075	0.0098	0.19	0.25	-
D	0.1890	0.1968	4.80	5.00	3
E	0.1497	0.1574	3.80	4.00	4
е	0.050	BSC	1.27 BSC		-
Н	0.2284	0.2440	5.80	6.20	-
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
Ν	ε	3	8		7
α	0 ⁰	8 ⁰	0 ⁰ 8 ⁰		-

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